

1/9

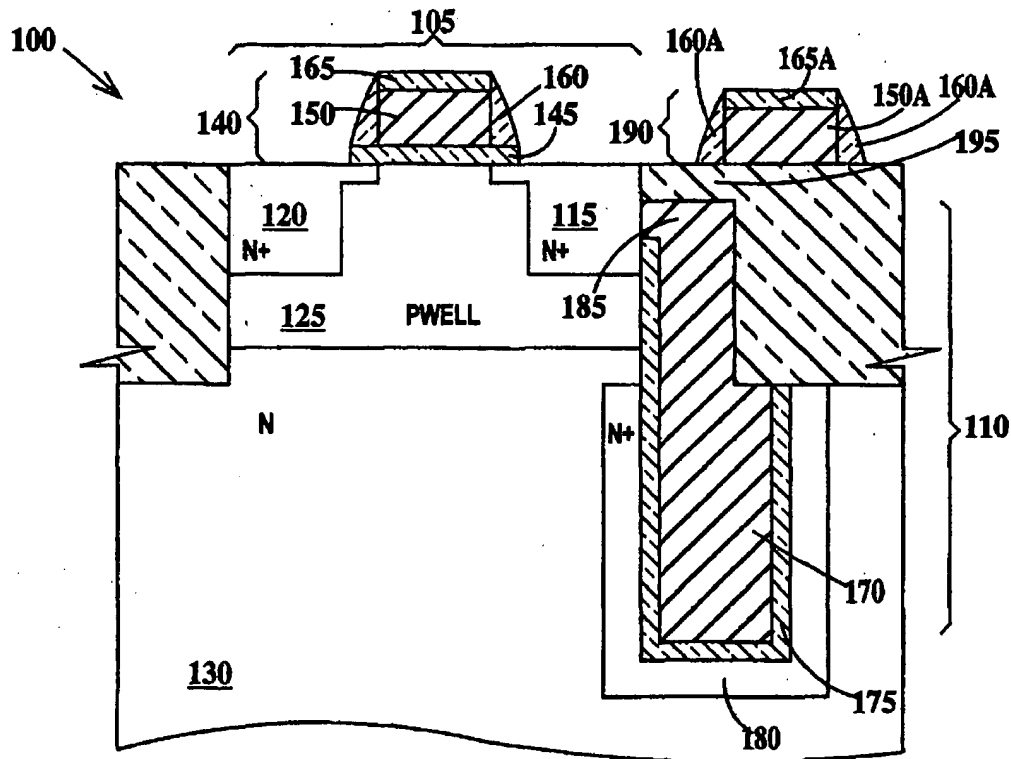


FIG. 1

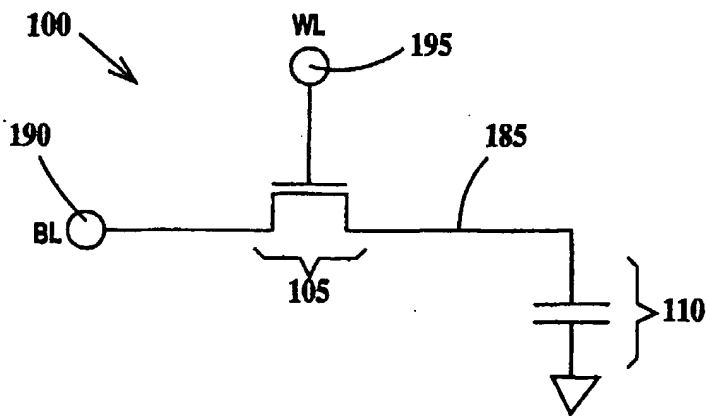


FIG. 2

2/9

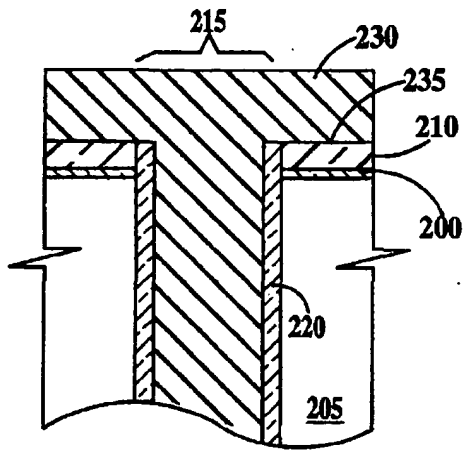


FIG. 3A

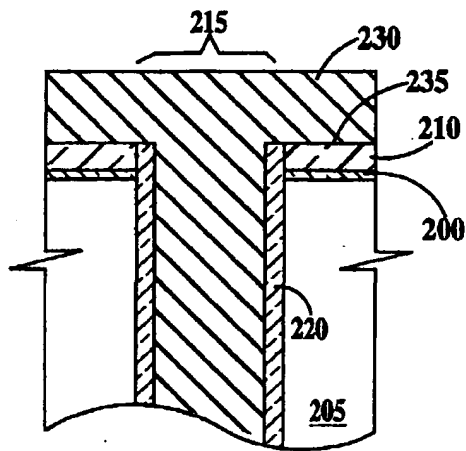


FIG. 4A

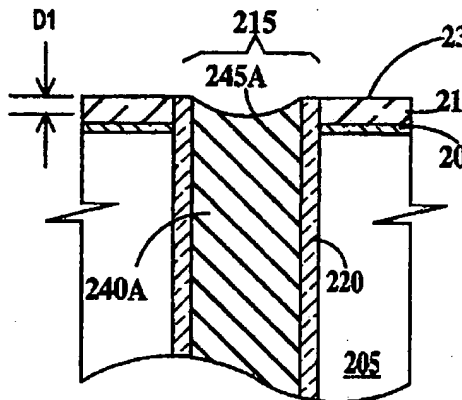


FIG. 3B

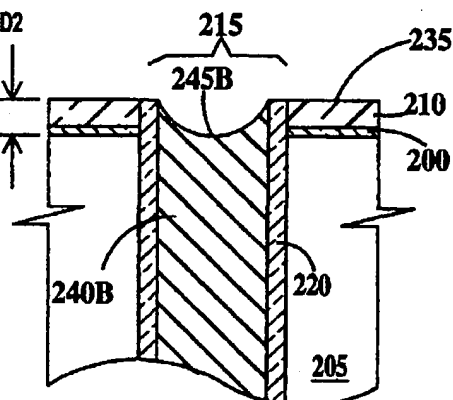


FIG. 4B

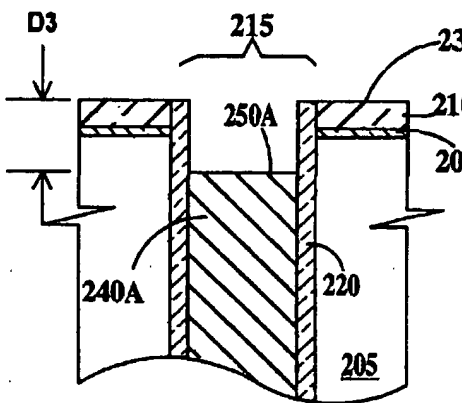


FIG. 3C

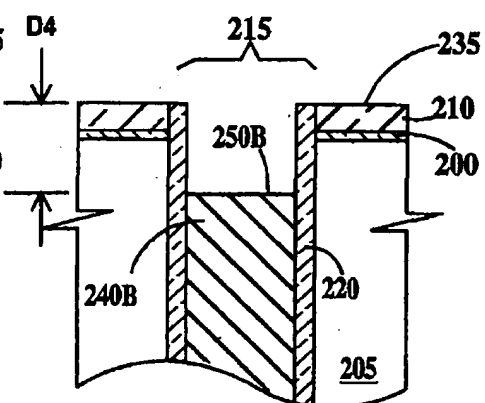


FIG. 4C

3/9

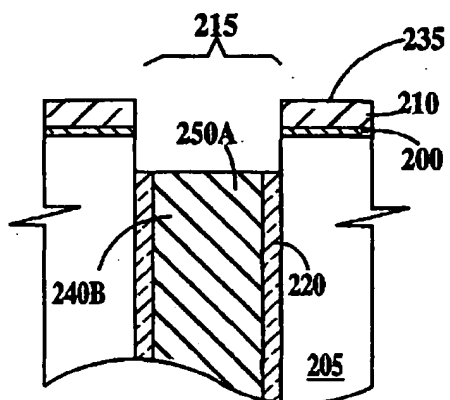


FIG. 3D

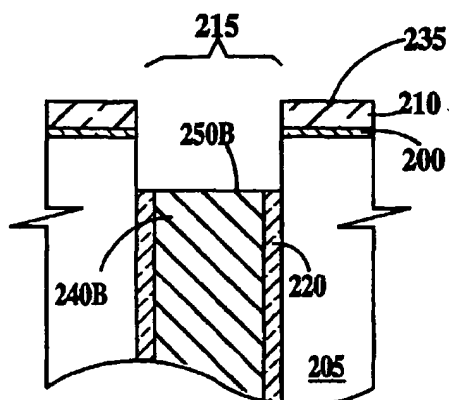


FIG. 4D

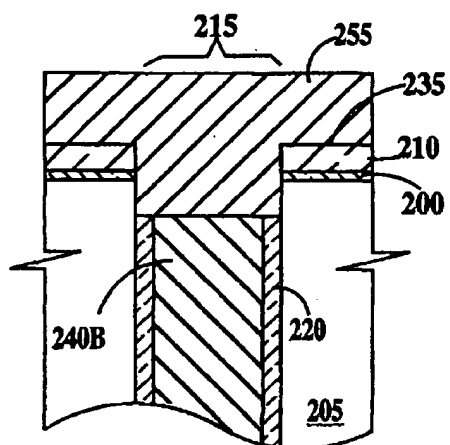


FIG. 3E

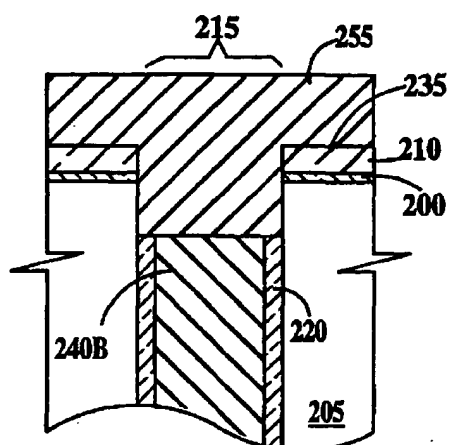


FIG. 4E

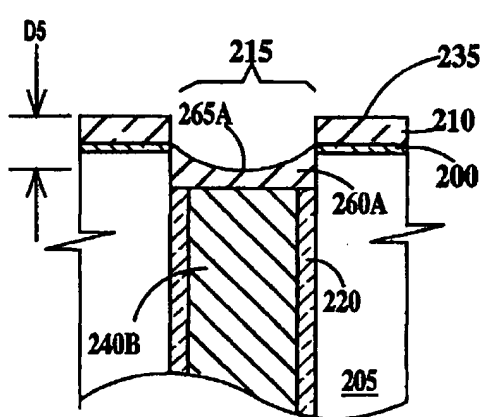


FIG. 3F

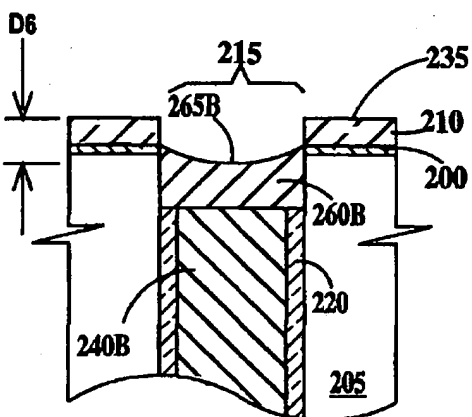


FIG. 4F

4/9

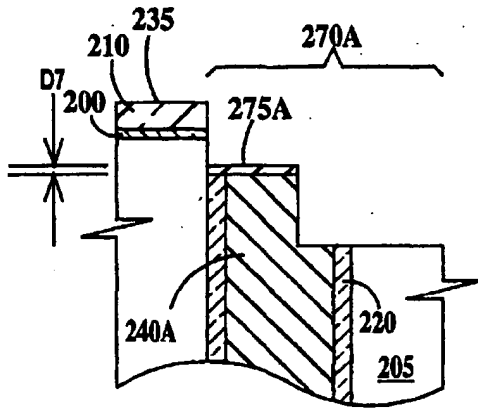


FIG. 3G

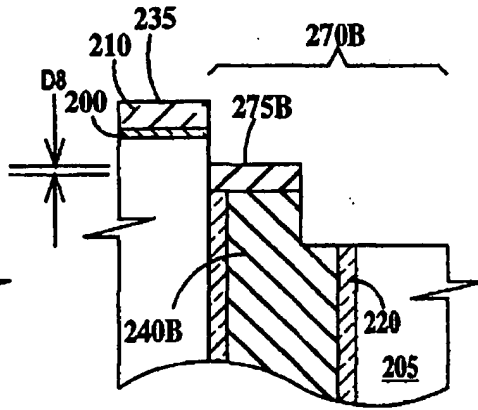


FIG. 4G

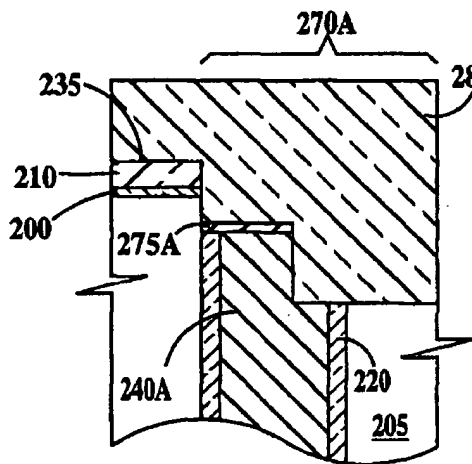


FIG. 3H

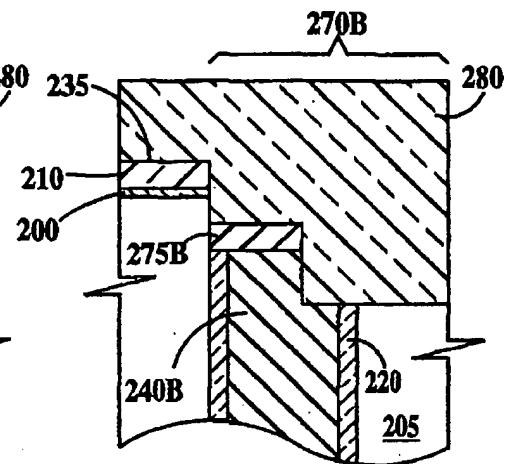


FIG. 4H

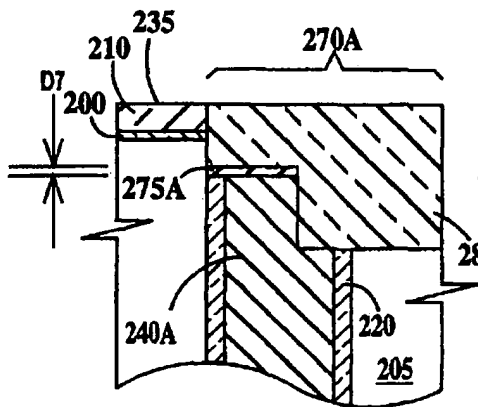


FIG. 3I

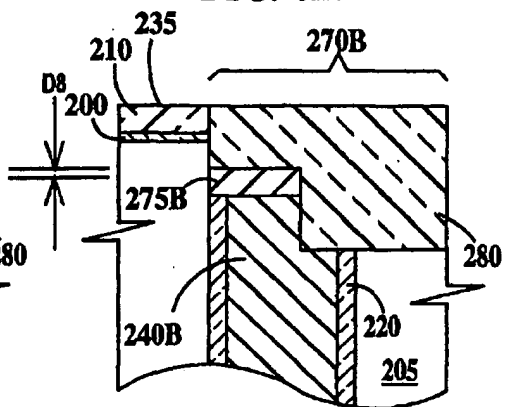


FIG. 4I

5/9

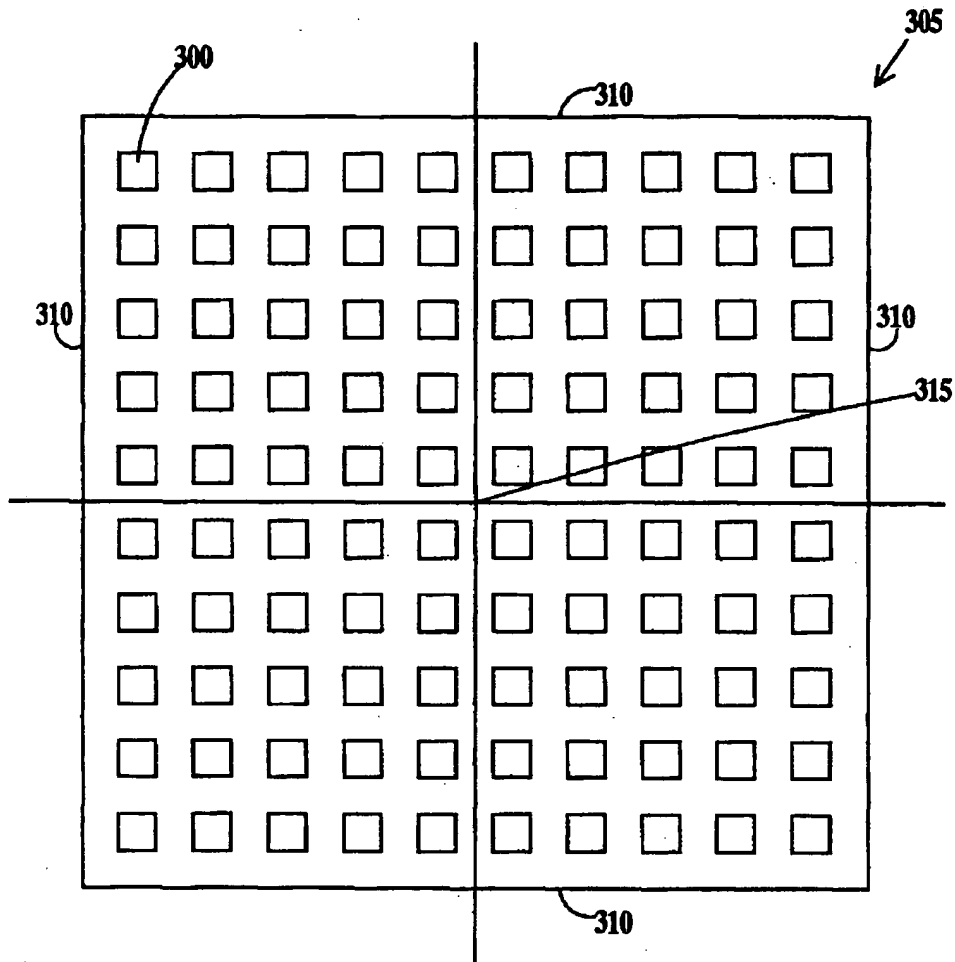


FIG. 5

6/9

**PAD NITRIDE THICKNESS
vs.
DISTANCE FROM EDGE OF ARRAY**

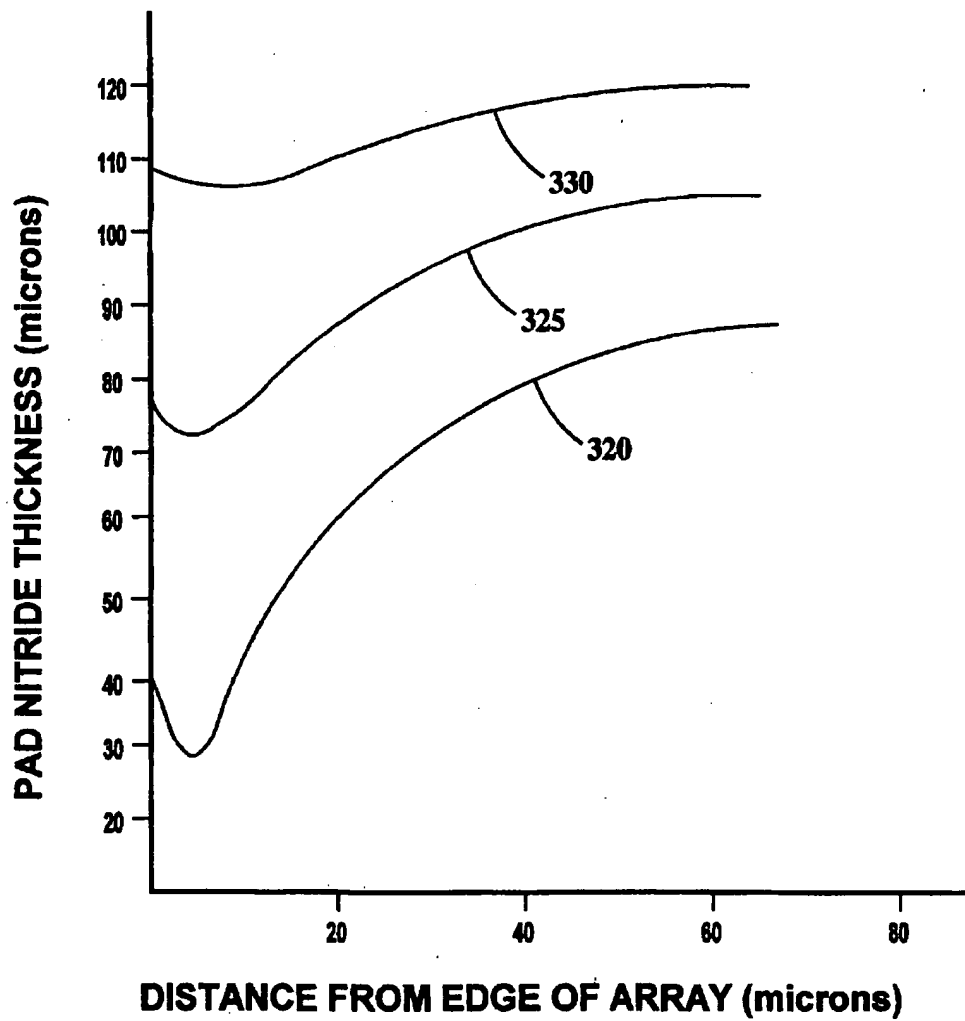


FIG. 6

7/9

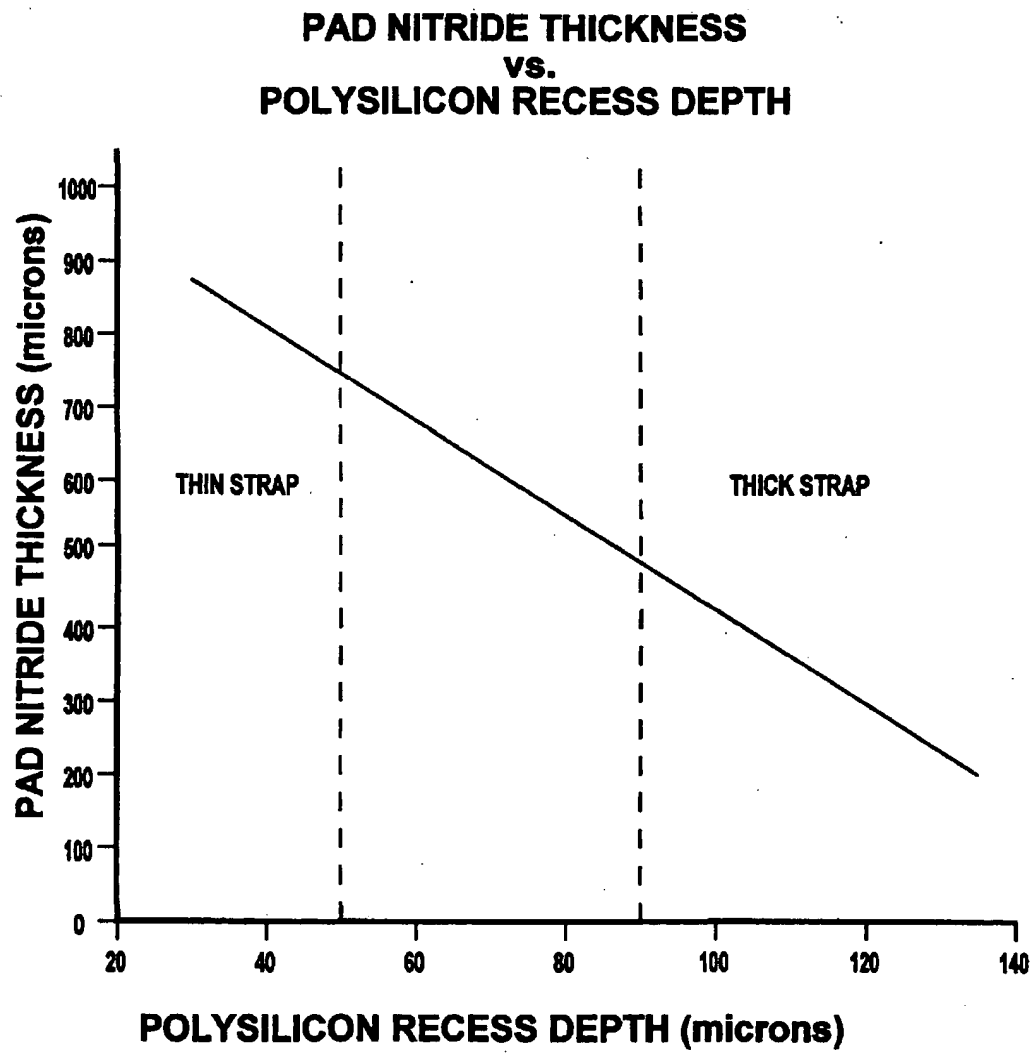


FIG. 7

8/9

**CMP TEMPERATURE
vs.
POLYSILICON DISHING**

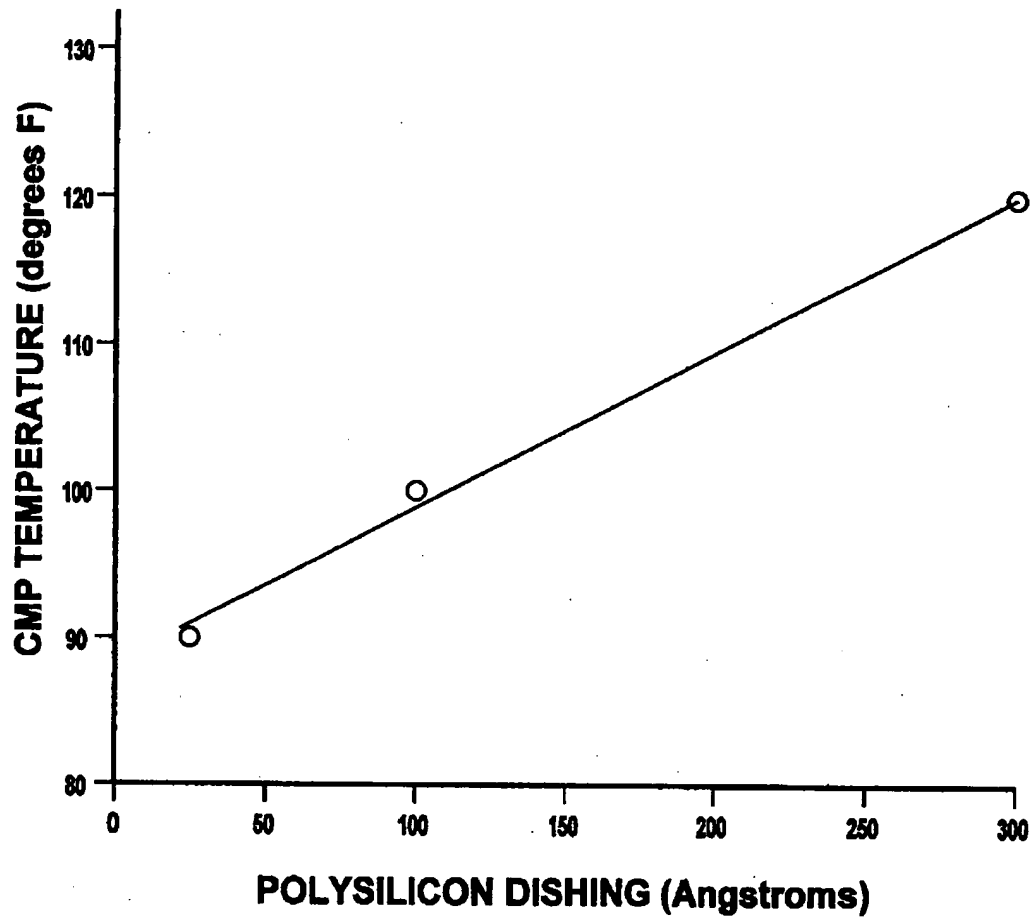


FIG. 8

9/9

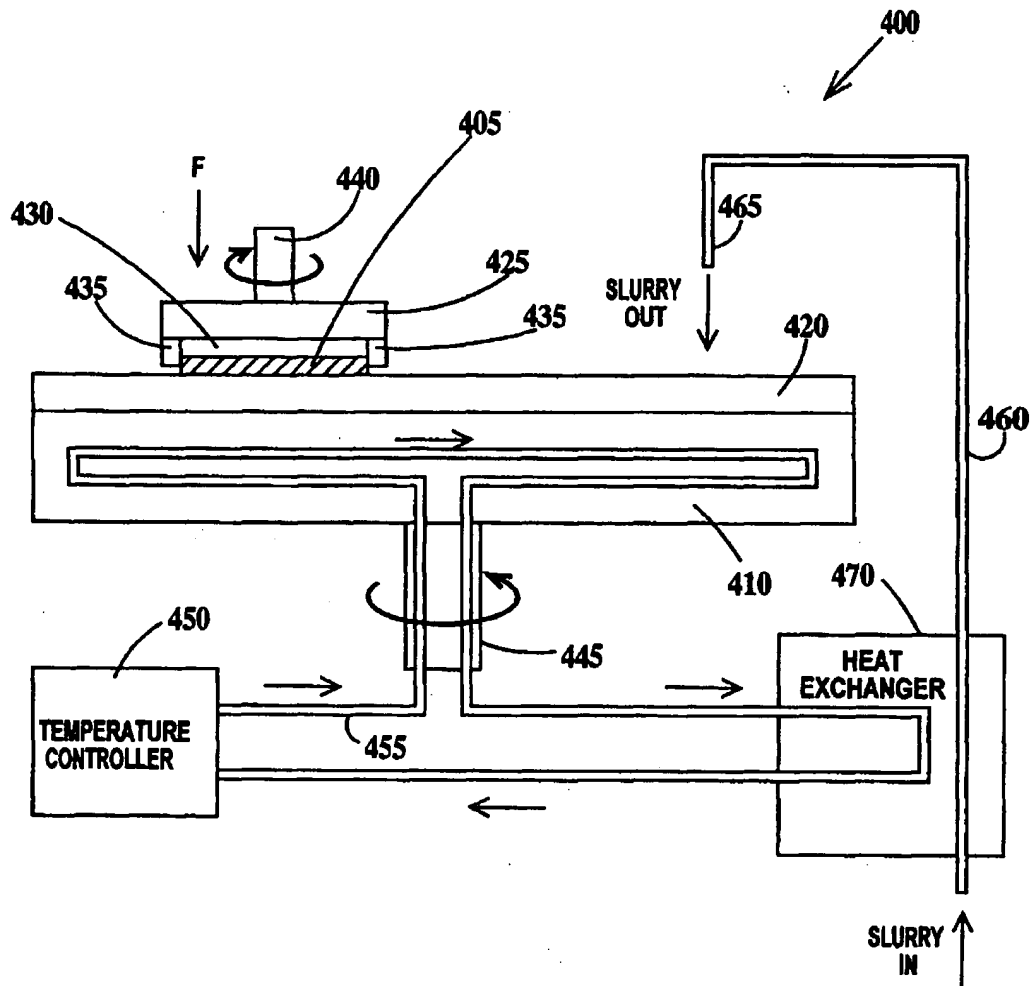


FIG. 9